

IEC QUALITY ASSESSMENT SYSTEM (IECQ) covering Electronic Components,

Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Approval Component Capability Approval

IECQ Certificate No.: IECQ-C BSI 15.0002

CB Certificate No.: E039/CA

| Schedule Number: | IECQ-C BSI 15.0002-S | Rev No.: 11 | Revision Date: 2015/05/ | (16 Page 1 of 2 |
|-------------------------------|--|--|-------------------------|--|
| Board Types: | Rigid single and double | BS 123100-003 | | |
| | Rigid double-sided with | plated-throug | h holes | BS 123200-003 |
| | Rigid multi-layer | BS 123300-003 | | |
| | Flexible single and dou connections | ble sided witho | out-through | BS 123400-003 |
| | Flexible double-sided w | BS 123500-003 | | |
| | Flex-rigid multi-layer wi | BS 123600-003 | | |
| Base Materials: | Epoxide Woven Glass Polyimide Film | | | |
| Board Size: | 610 mm x 457 mm 610 mm x 457 mm 610 mm x 457 mm 610 mm x 457 mm | Maximum Maximum Maximum Maximum | | BS EN 123 300 100, BS EN 123 200 400, BS EN 123 500 BS EN 123 600 |
| Conductors: | Minimum Width: Minimum Spacing: | 100 μm 100 μm | ± 25 μm ± 25 μm | |
| Number of Layers: | 24 Maximum | | | |
| Plated-through hole diameter: | 0.30 mm Minimum 0.30 mm Minimum | finished drilled | for component via hole | mounting |
| Aspect ratio: | 9 : 1 Maximum | | | |

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IECQ-CA Schedule of Scope Rev. 01



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|---------------------------|--|--|--------------------------------|-----------|-------------|--|
| Finishes: | * Hot Air Solder Levelling Liquid Photopolymer Solder Resist Legend; Thermally Cured ENIG surface finish | | | | | |
| Additional: | Bonded Hea | tsinks: | Anodised Alu | minium | | |
| | Blind and Bu Rigidisers / S | ıried Via Holes Stiffeners | | | | |
| * These finishes mee | t the solderability req | uirements after | r accelerated ageing |). | | |
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